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(54) **Silicon based substrate with yttrium silicate environmental/thermal barrier layer and method for preparing an article therefrom**

(57) A barrier layer for a silicon containing substrate which inhibits the formation of gaseous species of silicon when exposed to a high temperature aqueous environment comprises a yttrium silicate.

EP 1 044 944 A1

Description

[0001] The present invention relates to an article comprising a substrate containing silicon and a barrier layer which functions as a protective environmental/ thermal barrier coating and, more particularly, a barrier layer which inhibits the formation of gaseous species of Si, particularly $\text{Si}(\text{OH})_x$ when the article is exposed to a high temperature, aqueous (water and/or steam) environment.

[0002] Ceramic materials containing silicon and metal alloys containing silicon have been proposed for structures used in high temperature applications as, for example, gas turbine engines, heat exchangers, internal combustion engines, and the like. A particular useful application for these materials is for use in gas turbine engines which operate at high temperatures in aqueous environments. It has been found that these silicon containing substrates can recede and lose mass as a result of a formation volatile Si species, particularly $\text{Si}(\text{OH})_x$ and SiO when exposed to high temperature, aqueous environments. For example, silicon carbide when exposed to a lean fuel environment of approximately 1 ATM pressure of water vapor at 1200°C will exhibit weight loss and recession at a rate of approximately 6 mils per 1000 hrs. It is believed that the process involves oxidation of the silicon carbide to form silica on the surface of the silicon carbide followed by reaction of the silica with steam to form volatile species of silicon such as $\text{Si}(\text{OH})_x$. Naturally it would be highly desirable to provide an external barrier coating for silicon containing substrates which would inhibit the formation of volatile silicon species, $\text{Si}(\text{OH})_x$ and SiO , and thereby reduce recession and mass loss.

[0003] Accordingly, it is the principle object of the present invention to provide an article comprising a silicon containing substrate with a barrier layer which inhibits the formation of gaseous species of Si, particularly $\text{Si}(\text{OH})_x$, when the article is exposed to a high temperature, aqueous environment.

[0004] A second objective of this invention is to provide an article comprising a substrate with a barrier layer providing thermal protection, such layer closely matching the thermal expansion of the substrate.

[0005] It is a further object of the present invention to provide a method for producing an article as aforesaid.

[0006] The problems are solved by the teaching according to the independent claims. Particular developments are given in the dependent claims. Within the frame of the invention are all combinations of at least two of the descriptive elements and technical features disclosed in the claims and/or in the description.

[0007] The present invention relates to an article comprising a silicon containing substrate having a barrier layer on the substrate, wherein the barrier layer functions to both inhibit the formation of undesirable gaseous species of silicon when the article is exposed to a high temperature, aqueous environment and to provide thermal protection. By high temperatures is meant the temperature at which the Si in the substrate forms $\text{Si}(\text{OH})_x$ and/or SiO in an aqueous environment. By aqueous environment is meant a water and/or steam environment. The silicon containing composite is preferably a ceramic or metal alloy containing silicon. The external barrier layer is characterized by a coefficient of thermal expansion which is within plus or minus 3.0 ppm per degree centigrade of the coefficient of expansion of the silicon containing substrate. The preferred barrier layer in accordance with the present invention is a yttrium silicate barrier layer. In a preferred embodiment of the present invention the article can include one or more intermediate layers between the silicon based substrate and the barrier layer. The intermediate layer(s) and serve(s) to provide enhanced adherence between the barrier layer and the substrate and/or to prevent reactions between the barrier layer and the substrate.

[0008] The intermediate layer may comprise mullite or may be selected from the group consisting of SiO_2 , mullite, mullite-barium strontium aluminosilicate, mullite-yttrium silicate, mullite-calcium aluminosilicate, and silicon metal. In another embodiment the said intermediate layer may be selected from the group consisting of mullite, barium strontium aluminosilicate, mullite-yttrium silicate, calcium aluminosilicate and mixtures thereof. The said intermediate layer may comprise from about 40 to 80 wt.% mullite and from about 60 to 20 wt.% barium strontium aluminosilicate or yttrium silicate or calcium aluminosilicate.

[0009] The intermediate layer has a thickness of ≥ 0.5 mils (0.0005 inch), preferably a thickness of 3 to 30 mils or especially a thickness of 3 to 5 mils.

[0010] Within the frame of the invention is a bond layer between the substrate and the intermediate layer. This bond layer may be a silicon metal or SiO_2 . This bond layer has a thickness of between about 3 to 6 mils.

[0011] Preferably the aforesaid barrier layer has a thickness of between about 3 to 30 mils, especially a thickness of between about 3 to 5 mils.

[0012] The invention further relates to a method for producing an article comprising a silicon containing substrate and a barrier layer which inhibits the formation of gaseous species of silicon and/or provides thermal protection when the article is exposed to a high temperature, aqueous environment as defined above.

[0013] The method for preparing the article comprises the steps of:

providing a substrate comprising silicon; and

applying a yttrium containing barrier layer to the substrate wherein the barrier layer inhibits the formation of gaseous species of Si when the article is exposed to a high temperature, aqueous environment. The coefficient of ther-

mal expansion of the barrier layer may be within ± 3.0 ppm/ $^{\circ}\text{C}$ the coefficient of thermal expansion of the substrate or within ± 0.5 ppm/ $^{\circ}\text{C}$.

[0014] Within the frame of the invention is the step of grit blasting the substrate prior to applying the barrier layer. This step may include grit blast with alumina particles having a particle size of ≤ 30 microns, preferably grit blasting at a velocity of between about 150 m/sec to 200 m/sec.

[0015] The barrier layer may be applied by thermal spraying. This thermal spraying may include at a temperature of between about 800 $^{\circ}\text{C}$ to 1200 $^{\circ}\text{C}$.

[0016] Another step is to preoxidize the substrate to form a layer of SiO_2 prior to applying the barrier layer. The pre-oxidizing may comprise heating the substrate at a temperature of between about 800 $^{\circ}\text{C}$ to 1200 $^{\circ}\text{C}$ for about 15 minutes to 100 hours.

[0017] After applying the barrier layer, article should be heat treated. The heat treating comes to a temperature of about 1250 $^{\circ}\text{C}$ for about 24 hours.

[0018] Eventually the barrier layer comprises from about 66% by weight to about 78% by weight Y_2O_3 , balance essentially SiO_2 especially from about 75% by weight to about 76% by weight Y_2O_3 , balance SiO_2 .

[0019] Further advantages, characteristics and details of the invention are apparent from the following detailed description of preferred embodiments of the invention with reference to the attached drawing.

Figure 1 is a graph showing the stability of the barrier layer of the present invention with respect to recession and mass loss; and

Figure 2 is a photomicrograph through a sample of the barrier layer of the present invention on a silicon carbide substrate.

[0020] The present invention relates to an article comprising a silicon substrate and a barrier layer, wherein the barrier layer inhibits the formation of gaseous species of silicon when the article is exposed to a high temperature, aqueous environment. The invention also relates to a method for producing the aforesaid article. In addition, it should be appreciated that while the barrier is particularly directed to an environmental barrier layer, the barrier layer also functions as a thermal barrier layer and thus the present invention broadly encompasses the use of environmental/ thermal barrier layers on silicon containing substrates and on substrates having comparable thermal expansion coefficients.

[0021] According to the present invention, the silicon containing substrate may be a silicon ceramic substrate or a silicon containing metal alloy. In a preferred embodiment, the silicon containing substrate is a silicon containing ceramic material as, for example, silicon carbide, silicon nitride, silicon oxynitride and silicon aluminum oxynitride. In accordance with a particular embodiment of the present invention, the silicon containing ceramic substrate comprises a silicon containing matrix with reinforcing materials such as fibers, particles and the like and, more particularly, a silicon based matrix which is fiber-reinforced. Particularly suitable ceramic substrates are a silicon carbide coated silicon carbide fiber-reinforced silicon carbide particle and silicon matrix, a carbon fiber-reinforced silicon carbide matrix and a silicon carbide fiber-reinforced silicon nitride matrix. Particularly useful silicon-metal alloys for use as substrates for the article of the present invention include molybdenum-silicon alloys, niobium-silicon alloys, iron-silicon alloys, and aluminum-silicon alloys.

[0022] Barrier layers particularly useful in the article of the present invention include yttrium silicates. In particular, the barrier layer comprises Y_2O_3 in an amount of between about 66% by weight to about 78% by weight, balance SiO_2 , preferably between about 75% by weight to about 76% by weight Y_2O_3 , balance SiO_2 . A particularly suitable barrier layer for use on silicon containing ceramic compositions in the article of the present invention comprises about 75.45% by weight Y_2O_3 and 24.55% by weight SiO_2 .

[0023] It is an important feature of the present invention to maintain compatibility between the coefficient of thermal expansion of the silicon containing substrate and the barrier layer. In accordance with the present invention it has been found that the coefficient of thermal expansion of the barrier layer should be within ± 3.0 ppm per degrees centigrade, preferably ± 0.5 ppm per degrees centigrade, of the coefficient of thermal expansion of the silicon containing substrate. When using a silicon containing ceramic substrate such as a silicon carbide or a silicon nitride matrix with or without reinforcing fibers as described above in combination with the preferred yttrium silicate barrier layer of the present invention, the desired thermal compatibility with respect to expansion coefficient between the silicon containing substrate and the barrier layer should be ± 2.00 ppm per degrees centigrade.

[0024] The barrier layer should be present in the article at a thickness of greater than or equal to about 0.5 mils (0.0005 inch), preferably between about 3 to about 30 mils and ideally between about 3 to about 5 mils. The barrier layer may be applied to the silicon containing substrate by any suitable manner known in the art, however, it is preferable that the barrier layer be applied by thermal spraying as will be described hereinbelow.

[0025] In a further embodiment of the article of the present invention, an intermediate layer can be provided between the silicon containing substrate and the barrier layer. The intermediate layer(s) serve(s) to provide enhanced

adhesion between the barrier layer and the substrate and/or to prevent reactions between the barrier layer and the substrate. The intermediate layer consists of, for example, SiO_2 , mullite, mullite-barium strontium aluminosilicate, mullite-yttrium silicate, mullite-calcium aluminosilicate, and silicon metal. Mullite has been found to be a particularly useful intermediate layer; however, mullite by itself tends to be cracked as the result of thermal spraying fabrication processing. Accordingly, it is preferred that the barrier layer comprises mullite-barium strontium aluminosilicate, mullite-yttrium silicate, or mullite-calcium aluminosilicate in an amount of between about 40 to 80 wt.% mullite and between about 20 to 60 wt.% barium strontium aluminosilicate or yttrium silicate or calcium aluminosilicate. The thickness of the intermediate layer is typical to those described above with regard to the barrier layer and the intermediate layer may likewise be disposed in any manner known in the prior art, however, preferably by thermal spraying as described hereinbelow.

[0026] In addition to the intermediate layer, a bond layer may be provided between the silicon containing substrate and the intermediate layer. A suitable bond layer includes silicon metal in a thickness of 3 to 6 mils. Alternatively, the silicon based substrate may be pre-oxidized to provide a SiO_2 bond layer prior to application of the intermediate layer.

[0027] The method of the present invention comprises providing a silicon containing substrate and applying a barrier layer wherein the barrier layer inhibits the formation of gaseous species of silicon when the article is exposed to a high temperature, aqueous environment. In accordance with the present invention it is preferred that the barrier layer be applied by thermal spraying. It has been found that the barrier layer should be thermal sprayed at a temperature of between about 800°C to 1200°C in order to help equilibrate as-sprayed, splat quenched, microstructure and to provide a means to manage stresses which control delamination.

[0028] The silicon containing substrate should be cleaned prior to application of the barrier layer to remove substrate fabrication contamination. It is preferred that the silicon based substrate be subjected to a grit blasting step prior to application of the barrier layer. The grit blasting step must be carried out carefully in order to avoid damage to the surface of the silicon-containing substrate such as silicon carbide fiber reinforced composite. It has been found that the particles used for the grit blasting should not be as hard as the substrate material to prevent erosive removal of the substrate and the particles must be small to prevent impact damage to the substrate. When processing an article comprising a silicon carbide ceramic substrate, it has been found that the grit blasting should be carried out with Al_2O_3 particles, preferably of a particle size of ≤ 30 microns and, preferably, at a velocity of about 150 to 200 m/sec. In addition to the foregoing, it may be particularly useful to preoxidize the silicon based substrate prior to application of the intermediate and/or barrier layer in order to improve adherence. It has been found that bond layers of between 100 nanometers to 2000 nanometers are preferred. SiO_2 bond layers of the desired thickness can be achieved by preoxidizing the silicon carbide substrate at a temperature of between 800°C to 1200°C for about 15 minutes to 100 hours.

[0029] The silicon bond layer may be applied directly to the grit blasted surface by thermal spraying at approximately 870°C to a thickness of 3 to 6 mils.

[0030] Intermediate layers may be applied between the substrate and/or bond layer and the barrier layer or between the bond layer and barrier layer by thermal spraying in the same manner described above with respect to the barrier layer. As noted above, the preferred intermediate layers include mullite, mullite-barium strontium aluminosilicate, mullite-yttrium silicate, and mullite-calcium aluminosilicate.

[0031] After application of the desired layers to the silicon-based substrate material, the article is subjected to a heat treatment step in order to provide stress relief to the thermal sprayed structure, and to promote bonding between the sprayed powder particles and between the layers and the substrate. The heat treatment step is carried out at a temperature of about 1250°C for about 24 hours.

[0032] The advantages of the article of the present invention will become clear from consideration of the following examples.

Example 1

[0033] 0.9/1.1 mole ratio yttrium silicate specimens were fabricated via hot pressing in Argon at 1400°C for up to 250 thermal cycles in comparison to silicon carbide. The results show that the silicon carbide loses up to 8 mg/cm² weight during the testing while the yttrium silicate does not. See Figure 1.

Example 2

[0034] Figure 2 is a cross section of a 4 mil thick 0.9/1.1 mole ratio yttrium silicate of composition 0.9/1.1 mole ratio of yttria to silica coating on 4 mils of mullite on SiC composite. The yttrium silicate and mullite were thermal sprayed onto the silicon carbide composite using the following parameters:

	<u>Parameter</u>	<u>Setting</u>
5	plasma torch	Metco 3M
	nozzle	GH
	anode	std.
	powder port	metco #2
	primary gas	Ar @80 Metco gage
10	secondary gas	H2 @ 8 Metco gage
	substrate temp.	850°C
	carrier gas	Ar @ 37 Metco gage
	powder feed	15 to 25 gpm
		intermed. surface
15	power	30kw 25 kw
	stand-off	2.5 - 3" 5"

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[0035] Prior to coating the substrate was cleaned by grit blasting with 27 micron alumina particles at an impact velocity of 150 to 200 mps. The yttrium silicate powder was obtained from Novel Technologies, Cayuga, New York as a free flowing -200 + 400 mesh powder.

[0036] This invention may be embodied in other forms or carried out in other ways without departing from the spirit or essential characteristics thereof. The present embodiment is therefore to be considered as in all respects illustrative and not restrictive, the scope of the invention being indicated by the appended claims, and all changes which come within the meaning and range of equivalency are intended to be embraced therein.

Claims

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1. An article comprising:

a substrate comprising silicon; and
a yttrium containing barrier layer, wherein the barrier layer inhibits the formation of gaseous species of Si when the article is exposed to a high temperature, aqueous environment.

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2. An article according to claim 1 wherein the substrate is selected from the group consisting of silicon containing ceramic and metal alloys containing silicon.

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3. An article according to claim 2 wherein the substrate is a silicon containing ceramic selected from the group consisting of silicon carbide, silicon nitride, silicon oxynitride and silicon aluminum oxynitride.

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4. An article according to claim 2 wherein the substrate is a composite comprising a silicon based matrix and a reinforcing particle, wherein preferably said substrate is selected from the group consisting of silicon carbide fiber-reinforced silicon carbide matrix, carbon fiber-reinforced silicon carbide matrix and silicon carbide fiber-reinforced silicon nitride.

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5. An article according to claim 2 wherein said substrate is a silicon containing metal alloy selected from the group consisting of molybdenum-silicon alloys, niobium silicon alloys, iron-silicon alloys, and iron-nickel-silicon based alloys.

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6. An article according to claim 1 wherein the barrier layer comprises yttrium oxide or wherein the barrier layer comprises a yttrium silicate.

7. An article according to one of the claims 1 to 6 wherein the barrier layer comprises from about 66% by weight to about 78% by weight Y_2O_3 , balance essentially SiO_2 , preferably wherein the barrier layer comprises from about 75% by weight to about 76% by weight Y_2O_3 , balance SiO_2 .

8. An article according to one of the claims 1 to 7 wherein the coefficient of thermal expansion of the barrier layer is within ± 3.0 ppm/ $^{\circ}$ C the coefficient of thermal expansion of the substrate or wherein the coefficient of thermal expansion of the barrier layer is within ± 0.5 ppm/ $^{\circ}$ C the coefficient of thermal expansion of the substrate.
- 5 9. An article according to one of the claims 1 to 8 wherein the barrier layer has a thickness of ≥ 0.5 mils (0.0005 inch), preferably 3-5 mils.
- 10 10. An article according to one of the claims 1 to 9 including an intermediate layer between the substrate and the barrier layer.
- 10 11. An article according to claim 10 wherein said intermediate layer is selected from the group consisting of SiO_2 , mullite, mullite-barium strontium aluminosilicate, mullite-yttrium silicate, mullite-calcium aluminosilicate, and silicon metal or wherein said intermediate layer is selected from the group consisting of mullite, barium strontium aluminosilicate, mullite-yttrium silicate, calcium aluminosilicate and mixtures thereof.
- 15 12. An article according to claim 10 wherein said intermediate layer comprises mullite.
13. An article according to one of the claims 10 to 12 wherein said intermediate layer comprises from about 40 to 80 wt.% mullite and from about 60 to 20 wt.% barium strontium aluminosilicate or wherein said intermediate layer comprises from about 40 to 80 wt.% mullite and from about 60 to 20 wt.% yttrium silicate.
- 20 14. An article according to one of the claims 10 to 12 wherein said intermediate layer comprises from about 40 to 80 wt.% mullite and from about 60 to 20 wt.% calcium aluminosilicate.
- 25 15. An article according to one of the claims 10 to 14 wherein the intermediate layer has a thickness of ≥ 0.5 mils (0.0005 inch).
16. An article according to one of the claims 10 to 15 wherein the intermediate layer has a thickness of 3 to 30 mils, wherein preferably the intermediate layer has a thickness of 3 to 5 mils.
- 30 17. An article according to one of the claims 10 to 16 including a bond layer between the substrate and the intermediate layer.
18. An article according to claim 17 wherein the bond layer is silicon metal or SiO_2 .
- 35 19. An article according to claim 17 or 18 wherein the bond layer has a thickness of between about 3 to 6 mils.
20. An article according to claim 7 wherein the barrier layer has a thickness of between about 3 to 5 mils.
- 40 21. A method for preparing an article comprising the steps of:
providing a substrate comprising silicon; and
applying a yttrium containing barrier layer to the substrate wherein the barrier layer inhibits the formation of gaseous species of Si when the article is exposed to a high temperature, aqueous environment.
- 45 22. A method according to claim 21 further including the step of grit blasting the substrate prior to applying the barrier layer.
23. A method according to claim 21 or 22 including grit blast with alumina particles having a particle size of ≤ 30 microns, including preferably grit blasting at a velocity of between about 150/m/sec to 200/m/sec.
- 50 24. A method according to one of the claims 21 to 23 including applying the barrier layer by thermal spraying, including preferably thermal spraying at a temperature of between about 800°C to 1200°C .
- 55 25. A method according to one of the claims 21 to 24 including the step of preoxidizing the substrate to form a layer of SiO_2 prior to applying the barrier layer.
26. A method according to one of the claims 21 to 25 wherein the preoxidizing comprises heating the substrate at a

temperature of between about 800°C to 1200°C for about 15 minutes to 100 hours.

27. A method according to one of the claims 21 to 26 including the step of, after applying the barrier layer, heat treating the article.

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28. A method according to one of the claims 21 to 27 wherein the coefficient of thermal expansion of the barrier layer is within ± 3.0 ppm/°C the coefficient of thermal expansion of the substrate or wherein the coefficient of thermal expansion of the barrier layer is within ± 0.5 ppm/°C the coefficient of thermal expansion of the substrate.

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29. A method according to one of the claims 21 to 28 including heat treating at a temperature of about 1250°C for about 24 hours.

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30. A method according to one of the claims 21 to 29 wherein the barrier layer comprises from about 66% by weight to about 78% by weight Y_2O_3 , balance essentially SiO_2 , wherein preferably the barrier layer comprises from about 75% by weight to about 76% by weight Y_2O_3 , balance SiO_2 .

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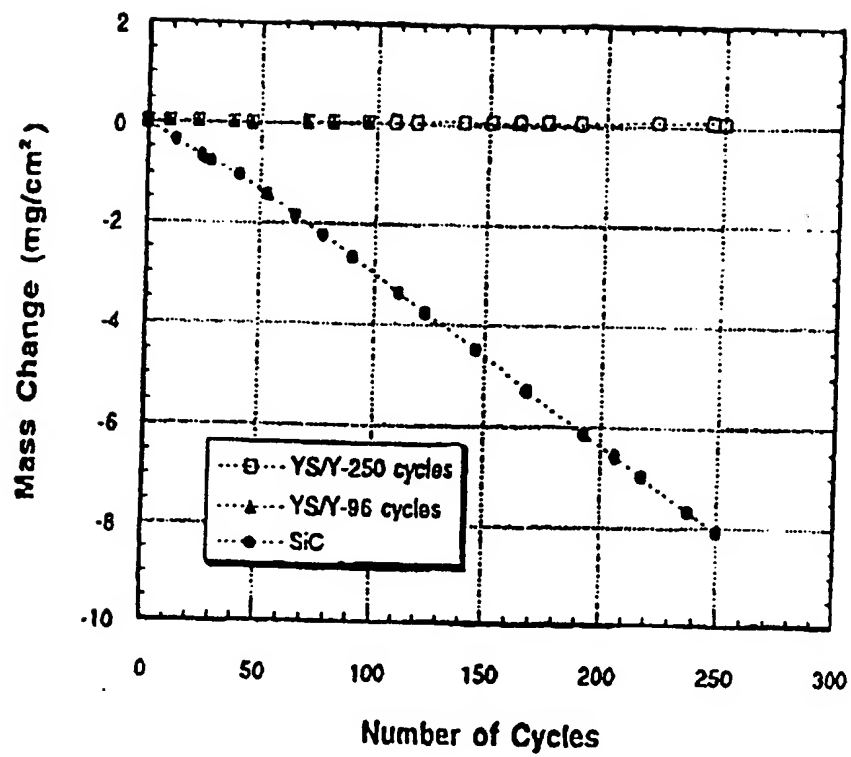
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Fig. 1

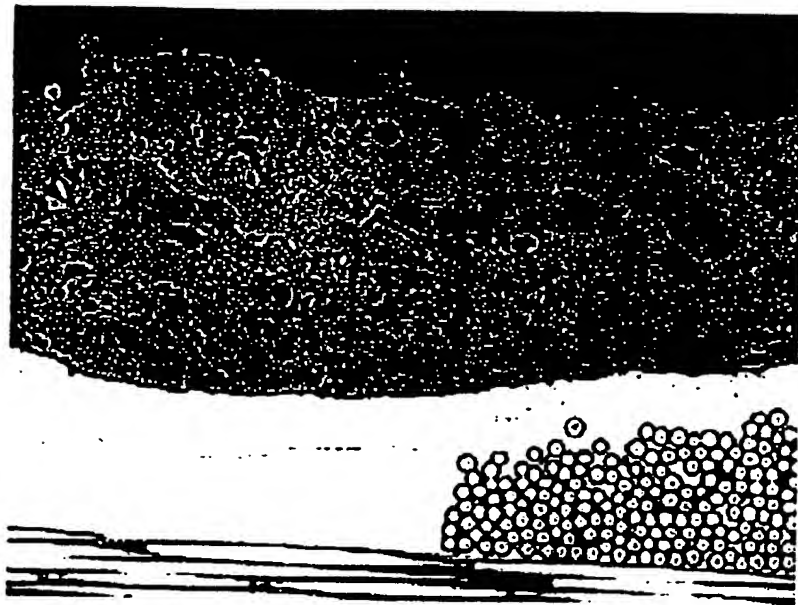


Fig. 2

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EUROPEAN SEARCH REPORT

Application Number
EP 00 10 8257

DOCUMENTS CONSIDERED TO BE RELEVANT			
Category	Citation of document with indication, where appropriate, of relevant passages	Relevant to claim	CLASSIFICATION OF THE APPLICATION (Int.Cl.7)
X	US 4 816 349 A (MATSUI MINORU ET AL) 28 March 1989 (1989-03-28) * column 2, line 16 - column 3, line 8 *	1-3,6, 21,22,24	C04B41/50 C23C4/04 C23C28/04 C04B41/52
X	EP 0 707 188 A (HALDENWANGER TECH KERAMIK GMBH) 17 April 1996 (1996-04-17) * claims 1,9,10 *	1-3,21, 22	
X	US 5 871 820 A (JOHNSON CURTIS ALAN ET AL) 16 February 1999 (1999-02-16) * claims 1,2 *	1-3,21	
			TECHNICAL FIELDS SEARCHED (Int.Cl.7)
			C04B C23C
The present search report has been drawn up for all claims			
Place of search MUNICH		Date of completion of the search 22 August 2000	Examiner Mini, A
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**ANNEX TO THE EUROPEAN SEARCH REPORT
ON EUROPEAN PATENT APPLICATION NO.**

EP 00 10 8257

This annex lists the patent family members relating to the patent documents cited in the above-mentioned European search report. The members are as contained in the European Patent Office EDP file on
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22-08-2000

Patent document cited in search report	Publication date	Patent family member(s)	Publication date
US 4816349 A	28-03-1989	JP 62030605 A	09-02-1987
		JP 1801712 C	12-11-1993
		JP 5008152 B	01-02-1993
		JP 62072582 A	03-04-1987
		EP 0211579 A	25-02-1987
		US 4882109 A	21-11-1989
		DE 3669872 D	03-05-1990
EP 0707188 A	17-04-1996	DE 4436823 C	02-05-1996
US 5871820 A	16-02-1999	DE 19680259 T	19-06-1997
		JP 10502133 T	24-02-1998
		WO 9631687 A	10-10-1996

EPO FORM P0459

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